5/3/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/512,968
Filing Date February 24, 2000
Inventor David R. Hembree
Assignee Micron Technology, Inc.
2858
Examiner V. Nguyen
Attorney's Docket No. MI22-1363
Title: Electronic Device Workpiece Processing Apparatus and Method of Communicating
Signals Within an Electronic Device Workpiece Processing Apparatus

INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether all the submitted references are prior art.

Dated: 4/30 0 l

Attorney:

Respectfully submitted,

James D. Shaurette Reg. No. 39,833

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| 1 Form PTO-1449 | | | U.S. PATI | U.S. DEFANTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | | ATTY. DOCKET NO. MI22-1363 | | | SERIAL NO. 09/512,968 | |
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| | | <u>o</u> | THER REFERE | NCES (including | Author, Title, Dat | e, Pertinent Pages, Etc.) | <u> </u> | | . Cl1.0/00/100md | |
| | AE | * 5/N: 09/032,184; F i | *3/N: 09/032,184; Eiled 2/27/98; Akram et al., Amendment filed 12/18/00; CPA filed 7/28/00; Amendment filed 3/3/00, Amendment filed 8/29/99; | | | | | | | |
| | | Original Application | Original Application filed 2/2/198; Pending Claims. | | | | | | | |
| | AF | Advertisement for P | Advertisement for Probe Technology; www.idinet.com; Interconnect Devices, Inc., 1 page; 3/6/98 | | | | | | | |
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| | AG | Good Things Come | Good Things Come In Small BGA/CSP Packages; www.johnstech.com/4/handbook/page9.html; 1 page; 3/5/98 | | | | | | | |
| | ! | | | | | | | | | |
| | AH | Product Description | Product Description for Double Ended Probes, B1052 Series; www.testprobe.com/products/b1052.html; Rika Denshi America, Inc.; 1 page; 2/4/98. | | | | | | | |
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| | AI | Product Description | for Test Center | s, RM-500 Series I | Probes, www.testpro | obe.com/products/rm500. | html; Rika De | enshi America, In | c.; 1 page; 2/4/98. | |
| | | | | | | | | | | |
| | ŸĪ | Product Description | Product Description for Cost Effective Interconnections for High I/O Products; www.testprobe.com/products/io.htm#b1303; Rika Denshi America, Inc.; | | | | | | | |
| | | 1 page; 2/4/98. | 1 page; 2/4/98. | | | | | | | |
| | AK Product Description for Ball Grid Probe B1303-C3; www.testprobe.com/products/io.htm#b1303; Rika Denshi America, Inc.; 1 page; 2/4/5 | | | | | | | | age; 2/4/98. | |
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| | AL | Product Description for Test Socket Contacts; www.johnstech.com/4/handbook/page9.html ; 1 page; 3/5/98 | | | | | | | | |
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| *EXAMINEI | R: Initial in | f reference considered, whether communication to applicant. | or not citation is | in conformance wit | th MPEP 609; Draw | v line through citation if r | ot in conform | ance and not cons | sidered. Include copy of | |